

Title (en)

Switch assembly and process for producing same

Title (de)

Schaltanordnung und Verfahren zu ihrer Herstellung

Title (fr)

Ensemble de commutation et son procédé de fabrication

Publication

EP 0982748 B1 20031105 (DE)

Application

EP 99810706 A 19990806

Priority

DE 19837945 A 19980821

Abstract (en)

[origin: JP2000067679A] PROBLEM TO BE SOLVED: To easily protect a switching device from the arc burning by mounting the plasma sprayed protective layers of the burning resistant material respectively on a point part of a contact tulip body of a first switching member and a point part of a switching pin of a second switching member. SOLUTION: In a switching device 10 comprising a first switching member provided with a contact tulip body 11 and a second switching member comprising a switching pin 14 vertically movable along a slide guide 13, the switching device is on and off by contacting and separating a point of a substrate 18 of the switching pin 14 with respect to a contact finger 25 of a substrate 26 of the contact tulip body 11. The protective layers 27, 29 are respectively formed on the point parts of the substrates 26, 28. This protective layers 27, 29 are formed by plasma spraying of the burning resistant material composed of, for example, about 80% of W and about 20% of Cu. Whereby the contact finger 25 and the point part of the switching pin 14 can be protected from the burning by an arc 17 generated in an arc chamber 16 in the switching-off.

IPC 1-7

H01H 33/91; **H01H 33/12**; **H01H 33/70**

IPC 8 full level

H01H 1/021 (2006.01); **H01H 1/04** (2006.01); **H01H 1/06** (2006.01); **H01H 1/38** (2006.01); **H01H 11/04** (2006.01); **H01H 31/02** (2006.01); **H01H 33/12** (2006.01); **H01H 33/70** (2006.01); **H01H 33/91** (2006.01)

CPC (source: EP US)

H01H 1/021 (2013.01 - EP US); **H01H 11/041** (2013.01 - EP US); **H01H 1/385** (2013.01 - EP US)

Cited by

DE10353497A1; CN109411263A; WO2005048281A1; US7679021B2; US10186389B2; WO2013093033A1; US9269514B2; US9443666B2; EP2909849B1

Designated contracting state (EPC)

CH DE FR IT LI

DOCDB simple family (publication)

DE 19837945 A1 20000224; CN 1132211 C 20031224; CN 1245964 A 20000301; DE 59907605 D1 20031211; EP 0982748 A1 20000301; EP 0982748 B1 20031105; JP 2000067679 A 20000303; US 6211478 B1 20010403

DOCDB simple family (application)

DE 19837945 A 19980821; CN 99118116 A 19990823; DE 59907605 T 19990806; EP 99810706 A 19990806; JP 23605099 A 19990823; US 37498499 A 19990816